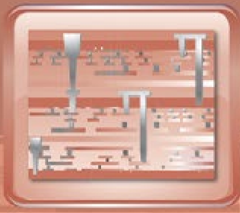

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ASME *Journal of Electronic Packaging*

Special Issue on InterPACK 2022

InterPACK is a premier, international forum for the exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronic packaging and micro/nano-electromechanical systems. It is also the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The *Journal of Electronic Packaging* (EP) publishes papers that use experimental and theoretical (analytical and computer-aided) methods, approaches, and techniques to address and solve various mechanical, material, thermal, and reliability problems encountered in the analysis, design, manufacturing, testing, and operation of electronic and photonics components, devices, and systems.

Topic Areas

- Advanced packaging
- Package assembly and architecture
- Reliability
- Thermal management and analysis
- Flexible electronics
- Advanced materials

Publication Target Dates

Paper submission deadline	**March 31, 2023**
Initial review completed	**June 30, 2023**
Special Issue publication date	**December 2023**

Submission Instructions

Papers should be submitted electronically to the journal at **journaltool.asme.org**. If you already have an account, log in as author to your ASME account. If you do not have an account, sign up for an account. In either case, at the **Paper Submittal** page, select the ***ASME Journal of Electronic Packaging*** and then select the Special Issue **InterPACK 2022.**

Papers received after the deadline or papers not selected for inclusion in the Special Issue may be accepted for publication in a regular issue.

Non-Standard Instructions

1. The Special Issue is targeted to publish honorary-quality papers from InterPACK 2022 that extend from the conference proceedings.
2. Please revise the original InterPACK 2022 conference paper with new content to meet a similarity requirement of <50%.
3. The submission should be directly revised from the InterPACK 2022 paper or technical presentation. Please include the original InterPACK paper in the appendix of your submission.

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